



LHC Upgrades

Silvia Gambetta

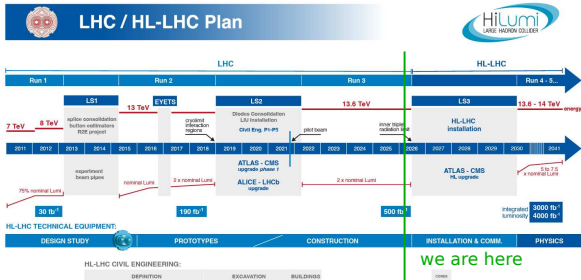
IOF Joint APP and HEPP Annual Conference 2026



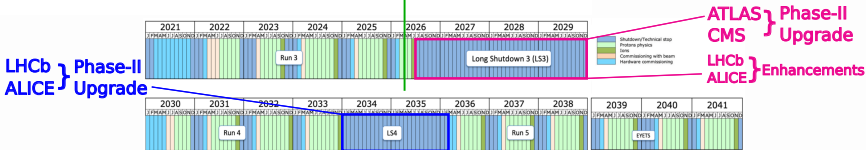
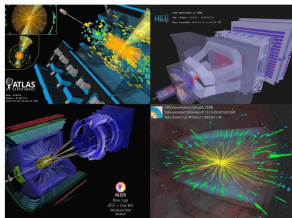
THE UNIVERSITY
of EDINBURGH



LHC Upgrades: when? Timeline of High Lumi projects



Event displays from 7 March, "last first injection" of Run3



Last months of Run 3 data taking ongoing: end of Run foreseen on the 30 June

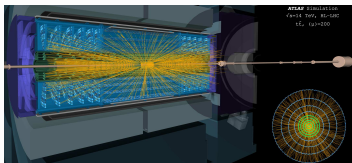
Last dance for many sub-systems with major Phase-II Upgrade foreseen for ATLAS and CMS, plus enhancement programmes in LHCb and ALICE [2026-2030]

Next major Upgrade foreseen in LS4 with Phase-II Upgrade foreseen for ALICE and LHCb [2034-2036]

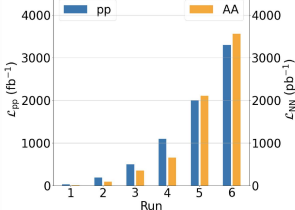
LHC Upgrades: what? A data driven era

“The full exploitation of the physics potential of the LHC and the HL-LHC and the completion of the high-luminosity upgrade remain the highest priorities of European particle physics.” [CERN-ESU-2025-002]

- Unprecedented pile-up conditions and track density
- Challenging radiation doses
- Huge volume of data to handle



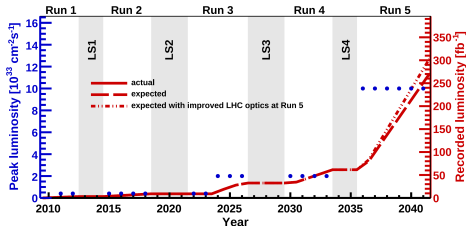
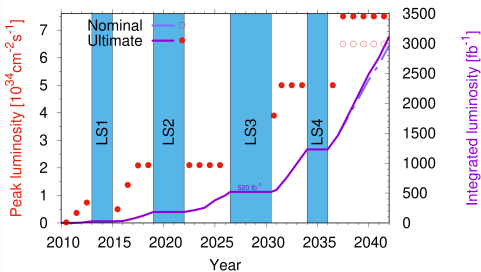
Nucleon-nucleon luminosities



← ALICE

LHCb →

ATLAS and CMS ↓

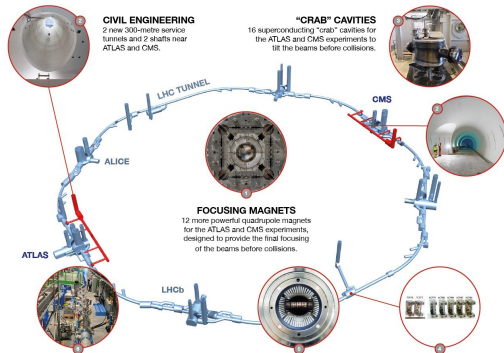


Huge volume of data to probe the Standard Model, perform precision measurements reaching theoretical uncertainties and search for New Physics

LHC Upgrades: how? Build a new machine

<https://hilumilhc.web.cern.ch/>

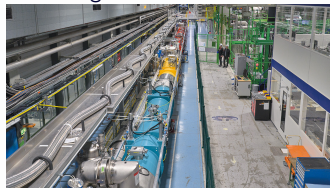
NEW TECHNOLOGIES FOR THE HIGH-LUMINOSITY LHC



Crab cavities



95 m long test stand



Preparation of a magnet and transfer of the beam screen to a movable bench



LHC Upgrades: but how? Build new experiments



Physics motivations and Scoping scenarios

Preparation for Upgrades takes over a decade

Our mantra: “Measure what is measurable and make measurable what is not so.” G. Galilei

Intensity and precision frontier at High Lumi LHC still has a lot to deliver: less than 20% of the LHC data will be collected by the end of Run3

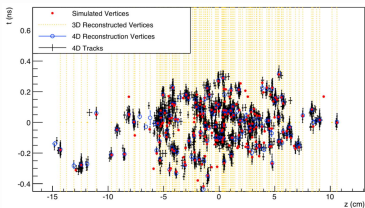
LHCC-G-166
ATLAS-TDR-025
ATLAS-TDR-030
ATLAS-TDR-031
ATLAS-TDR-022
ATLAS-TDR-028
ATLAS-TDR-026
ATLAS-TDR-029

LHCC-G-165
CMS-TDR-014
CMS-TDR-020
CMS-TDR-019
CMS-TDR-023
CMS-TDR-016
CMS-TDR-021
CMS-TDR-022

LHCB-TDR-026
LHCB-TDR-024
LHCB-TDR-025

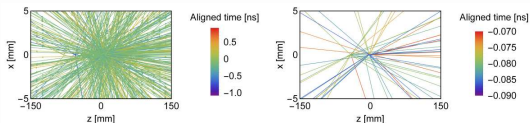
LHCC-G-185
ALICE-TDR-022
ALICE-TDR-021

Faster: Timing



From MIP TDR

Exploit the separation in both **time** and **space** of the pp collisions: separation in time corresponds essentially to the time-of-flight for the length of a bunch



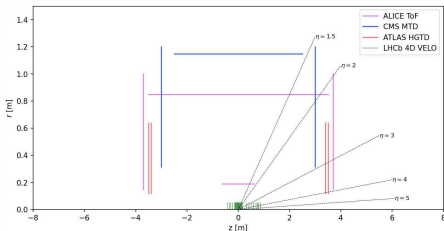
From LHCb Framework TDR

$\sigma_t = \sigma_{\text{bunch}}/\sqrt{2}c \sim 180 \text{ ps} \Rightarrow$ time resolution
tens of ps $\ll \sigma_t$

- ALICE 3 Time Of Flight (TOF) $\sim 20 \text{ ps}$
- ATLAS High Granularity Timing Detector (HGTD) $\sim 50 \text{ ps}$
- CMS MIP Timing Detector (MTD) $\sim 30 - 50 \text{ ps}$
- LHCb 4D VERtEX LOcator (VELO) $< 20 \text{ ps}$

See excellent review of timing in trackers by G. Pizzati at LHCP 2025

Timing is a key technique in LHC Upgrades also beyond tracking



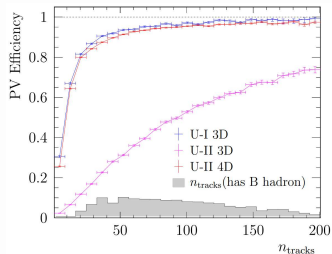
Detector	Acceptance	Technology	Pitch	Layers
HGTD	$2.4 < \eta < 4.1$	Silicon/LGAD	1.3 mm	4+4
Barrel TOF	$ \eta < 1.75$	Silicon	1 \rightarrow 5 mm	1+1
Forward TOF	$1.75 < \eta < 4$	Silicon	1 \rightarrow 5 mm	1+1
BTL	$ \eta < 1.45$	LYSO+SIPM	$\sim 3 \text{ mm}$	1
ETL	$1.6 < \eta < 3.0$	Silicon/LGAD	1.3 mm	4+4
VELO	$2 < \eta < 5^*$	Silicon	$\leq 55 \mu\text{m}$	$> 26 ?$

Faster: LHCb Velo

4D VERtEx LOcator in LHCb for time stamping of Primary Vertexes

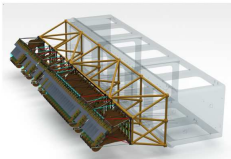
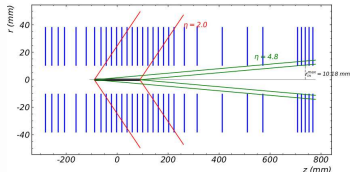
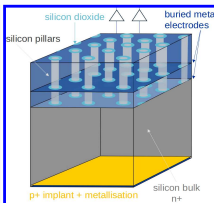
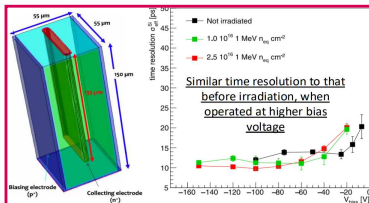
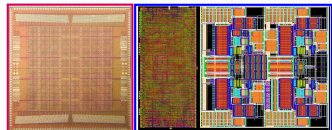
Run 5

- Introduction of timing essential to retain PV reconstruction efficiency in LHCb Upgrade II conditions
- 3D Sensors: ideal solution for both timing and radiation-tolerance
- Timing and radiation tolerance proven with **trench-type silicon sensors** [TimeSpot]
- R&D at early stage on **Silicon Electron Multiplier** to study potential for high electric field [SiEM]



Two ASICs considered (28nm CMOS)

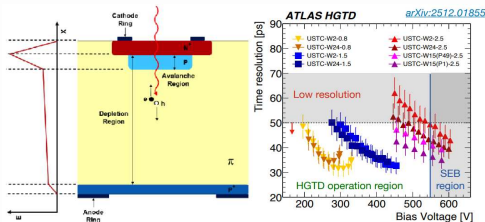
- **IGNITE**: 3D integration (one ASIC for analog, one for digital)
- **Picopix**: On-pixel analog power drop compensation



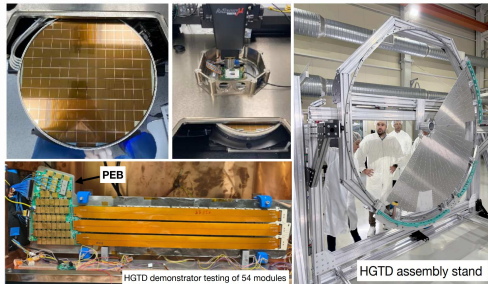
Faster: ATLAS HGTD

High Granularity Timing detector in ATLAS for time stamping tracks

Run 4

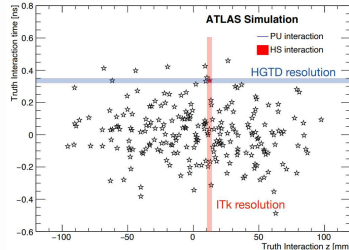


LGAD selected as sensors [characterisation on beam]
(15x15 pads, 1.3x1.3 mm² pad size, 775 μ m device thickness, 50 μ m active region)

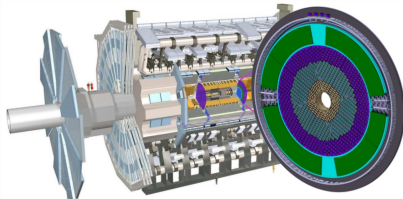


Vertex time information as new dimension to identify pileup

Instruments the forward region: 3.6M channels



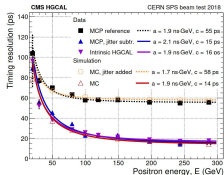
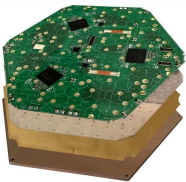
ALTIROC as ASIC: 17 wafers \sim 2000 ASIC probed for preproduction



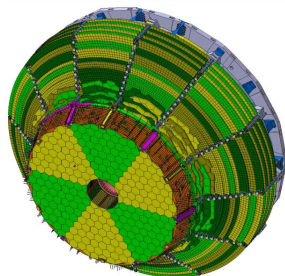
Faster: CMS HGICAL

High-Granularity Calorimeter in CMS for timing of showers

- **Electromagnetic** section: Silicon with Pb and CuW absorbers, 6M silicon pads (620 m²)
- **Hadronic** section: Silicon + scintillator with Cu absorbers, 240000 plastic scintillator tiles + SiPM (370 m²)



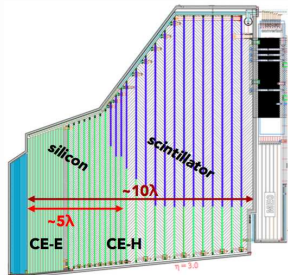
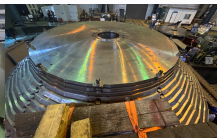
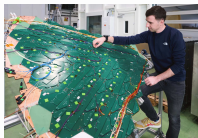
Run 4



8" Silicon sensors embedded in Hexagonal silicon modules

SiPMs read out by variant of HGCROC ASIC

Timing performance verified on testbeam [see results]

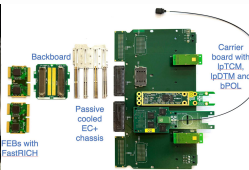
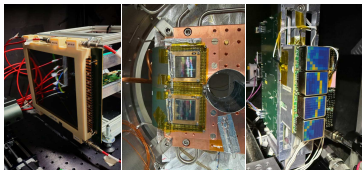
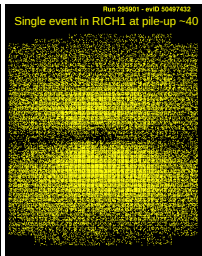
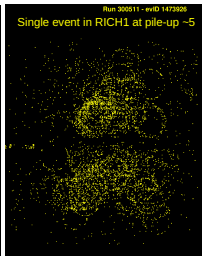
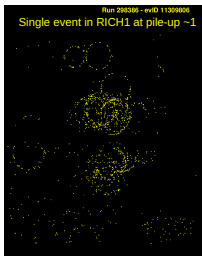


Faster: LHCb RICH

Ring Imaging Cherenkov detectors at LHCb for timing of Cherenkov rings

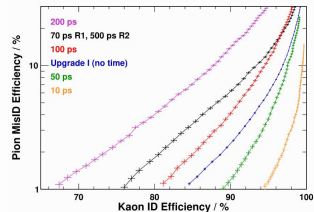
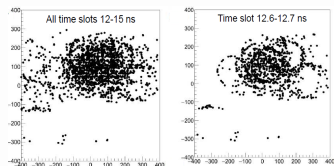
Run 4-5

- new optics and layout to reduce peak occupancy
- timing as key ingredient to retain the Particle Identification performance



FastRICH ASIC already design and version 0 being validated for the RICH LS3 Enhancement programme (replacement of FE electronics to anticipate time-resolved RICH and introduction of timing in LHCb)

LHCb-TDR-024



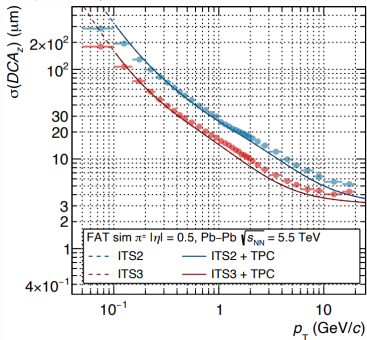
LHCb-TDR-023

Higher coverage: ALICE ITS3

Inner Tracker System 3 at ALICE

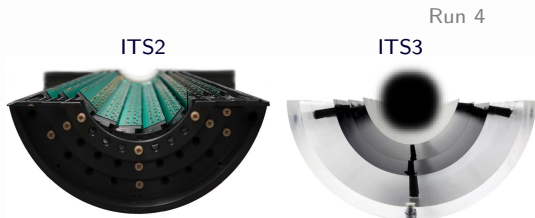
- move closer to the beam-pipe (24 mm \rightarrow 19 mm)
- minimise material budget (0.36 \rightarrow 0.07X/X₀ per layer)
- improve pointing resolution

ALICE-TDR-021

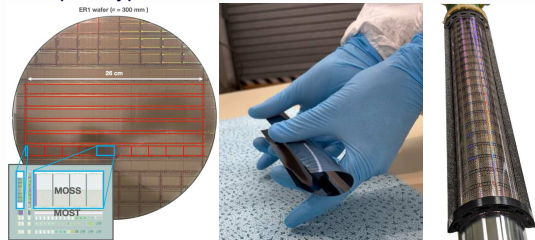


Can bent silicon work?

[Operations on beam]



First MOⁿolithic Stit^hed Sensor (MOSS) for HEP:
14x259 mm², 6.72 Mpixel
MOSAIX: ITS3 scale, 3 ASICs stitched together \rightarrow full scale prototype



Engineering Run 2 wafers received

Higher coverage: CMS tracker

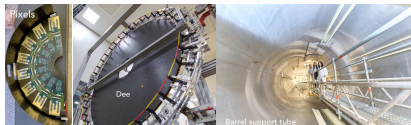
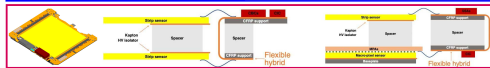
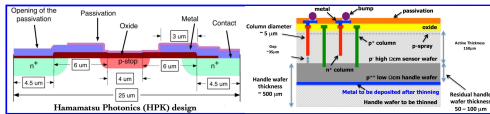
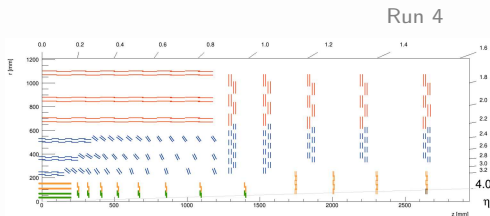
CMS-TDR-014

Inner Tracker

- 4 barrel layers,
- 8 small disks, 4 large discs per side
- Pixel size: $25 \times 100 \mu\text{m}^2$
- 2×109 channels

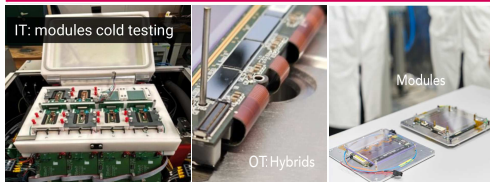
Outer Tracker

- 6 barrel layers
- 5 discs per side
- 44 million strips
- 174 million macropixels



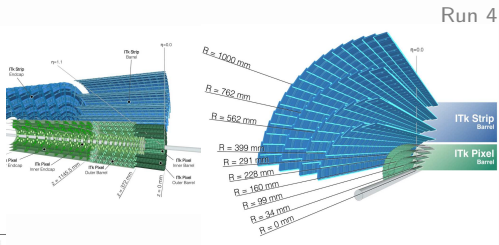
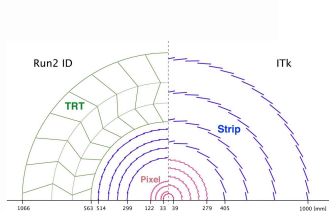
A. Canepa, LHCP 2025

Module in production stage: assembly ongoing for both IT and OT in production centres



Higher coverage: ITK

Inner Tracker at ATLAS



Pixel detectors (inner part)

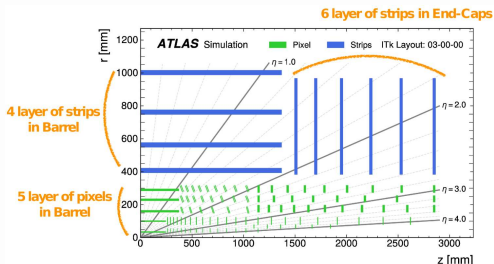
[ATLAS-TDR-030]

- 5 billion channels
- 5 layers of pixels in Barrel
- Many disks in End-Cap

Strip detectors (outer part)

[ATLAS-TDR-025]

- 60 million channels
- 4 layers of strips in Barrel
- 6 layers of strips in End-Cap



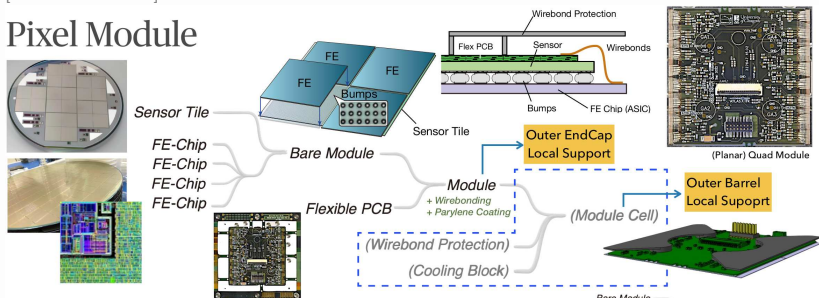
Compared to current detector (ID): Improved tracking acceptance from $|\eta| < 2.5$ to $|\eta| < 4$

	Area (in m ²)	# modules	# channels (in M)
ID Pixel	~ 2	~ 2000	~ 92
ITk Pixel	~ 13	~ 8400	~ 5100

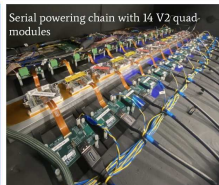
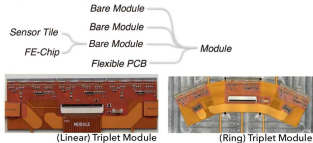
Unprecedented scale of massive silicon detector production

[H. Oide LHCP 2025]

Pixel Module



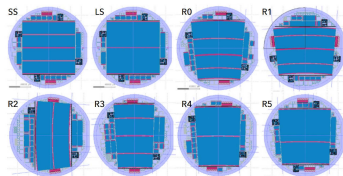
- Quad modules for outer barrel/endcap regions use 4 FE chips for covering a 4cm x 4cm large area pixel sensor tiles.
 - ▶ Attach wirebond protection CFRP and local cooling block cell for Outer Barrel.
- Triplet modules for inner regions have 1:1 mapping of a sensor and a FE chip.
- Approx. 12,000 modules will be produced (accounting production yield).
 - ▶ Module assembly & testing involves 10 assembly clusters across the Globe.



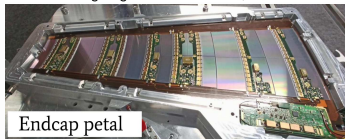
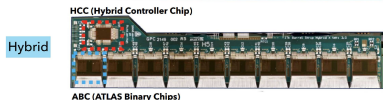
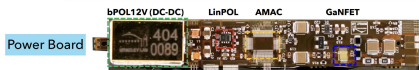
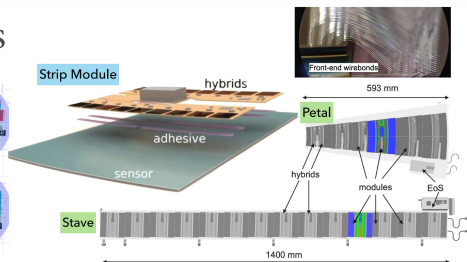
[H. Oide LHCP 2025]

Strip Sensors / Modules

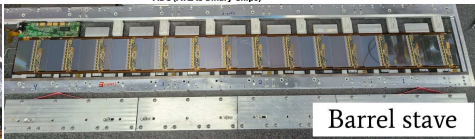
Short Strip (SS) - Long Strip (LS)



- Strip sensors have 8 different flavors.
 - AC coupled strips; n⁺-in-p type
 - Radiation-tolerant up to $\sim 1e15$ n_{ec}/cm²
 - SS/LS for barrel, R0-R5 for endcap.
- All types sensors are assembled as modules in a common concept.
 - Power board (bPOL12V DC-DC, LinPOL, mon & ctrl. chip AMAC)
 - "Hybrid" (Flexible PCB with ctrl. chip (HCC) and ABCs)
 - Direct gluing on the sensor and 5,200 wirebonds / module.



Endcap petal



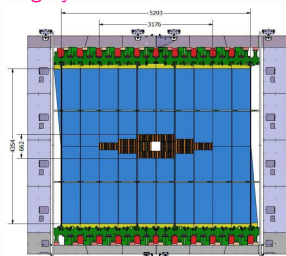
Barrel stave

[LHCC Open session]

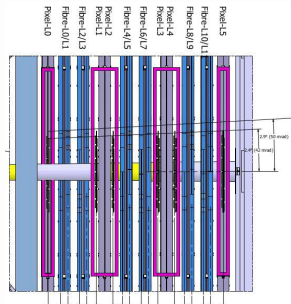
Higher coverage: LHCb Mighty Tracker

Run 5

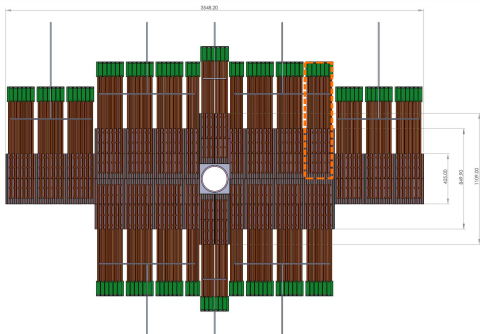
Mighty Tracker at LHCb



[LHCb-TDR-023] [LHCb-TDR-026]



- Inner region based on silicon detector technology (**Mighty-Pixel**)
- Scintillating fibres (**Mighty-SciFi**) cover most of the surface

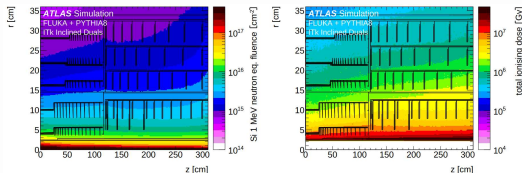


- **MT-Pixel**: Based on HV-CMOS design based on the experience of ATLASPix and MuPix (**MightyPix**) and alternative HV-CMOS (**RadPix**) → 6 layers, 2.4 m² each, for a total of 14 m²
- **MT-SciFi**: over 10000 km of scintillating fibres, coupled with SiPMs at cryogenic temperatures

Stronger: Radiation hardness

Trends in **silicon** sensors presented here (not a review)

Detector	Fluence [1 MeV n_{eq} cm^{-2}]
Alice ITS3	4×10^{12}
MT-Pixel	1×10^{14}
ATLAS ITK	1.4×10^{16}
CMS HGCAL	1.5×10^{16}
CMS IT	1.9×10^{16}
Velo LHCb	2.5×10^{16}



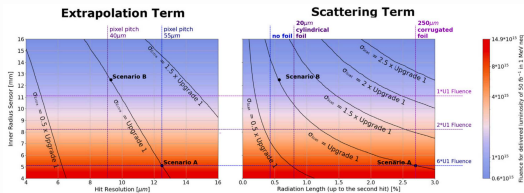
[ATLAS-TDR-030]



	Dose MGy	Fluence [10^{16} MeV n_{eq} cm^{-2}]
Alice ITS	0.01	10^{-3}
LHC	1	0.1-0.3
HL-LHC	5	1.5
FCC-hh	10-350	3-100

Monolithic sensors are an increasing trend, key development for long term plans in HEP

[see Walter Snoeys' seminar]



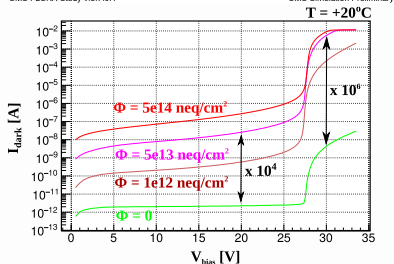
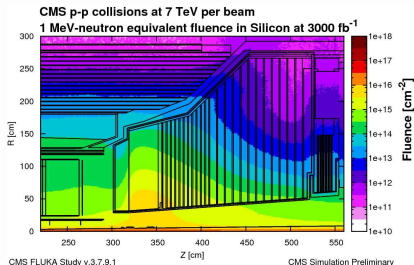
[Velo readout studies]

Balance in IP, distance between first sensor at interaction point, η coverage together with radiation levels expected

Stronger: Radiation hardness

Trends in SiPMs (not a review)

SiPMs employed in calorimetry, tracking and now increasing trend in PID (both ALICE3 and LHCb Upgrade II)



<https://doi.org/10.1016/j.nima.2017.11.003>

From E. Garutti's summary of radiation effects in SiPMs at PD2025

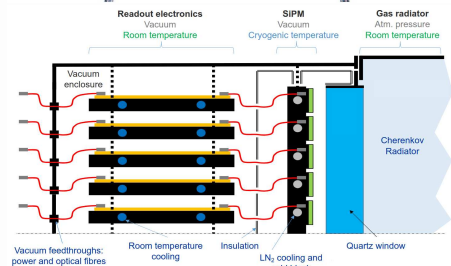
Some requirements examples:

- Imaging calorimeters for collider experiments: Hadronic calorimeter for lepton collider (CALICE)
→ $\phi_{\text{eq}} \sim 10^{10} \text{ cm}^{-2}$ after 500 fb⁻¹
- Upgrade of CMS hadronic calorimeter (HGCAL) → $\phi_{\text{eq}} \sim 5 \times 10^{13} \text{ cm}^{-2}$ after 3000 fb⁻¹
- New CMS MIP timing detector
→ $\phi_{\text{eq}} \sim 2 \times 10^{14} \text{ cm}^{-2}$ after 3000 fb⁻¹
- RICH detectors at EIC: Single photon detection up to → $\phi_{\text{eq}} \sim 2 \times 10^{10} \text{ cm}^{-2}$
- Space experiments: High radiation expected for detectors in space
→ $\phi_{\text{eq}} \sim 5 \times 10^{10} \text{ cm}^{-2}$, AGILE gamma ray detector

⇒ Operating temperature is a key ingredient to cope with increased DCR

Increased complexity

SiPMs @HGCal operated at -35° with CO_2 cooling

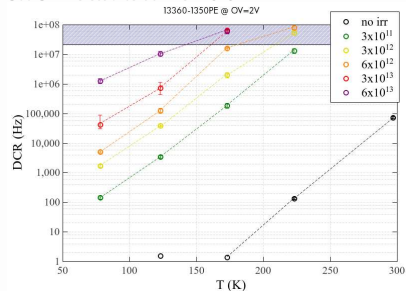


Increased complexity in mechanics and services

See Cryo demonstrator studies at RICH2025

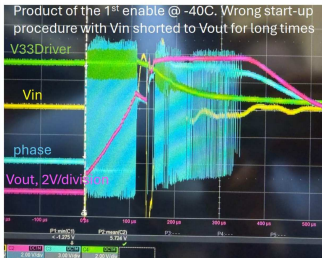
SiPMs @LHCb RICH at cryogenic temperatures to operate in single photon mode ($\phi_{\text{eq}} \sim 3 \times 10^{13} \text{ cm}^{-2}$ after 300 fb^{-1})

See SiPMs studies at RICH2025



Stronger: The curious case of the bPOL

Issue with bPOL12V discovered in Summer 2025 by ATLAS Inner-Tracker: strip modules irradiated to 70 Mrad (during a study dedicated to gluing process).



Courtesy of ATLAS-ITK, Freiburg

Some pictures of the test campaign



Courtesy of K. Wyllie and S. Baron

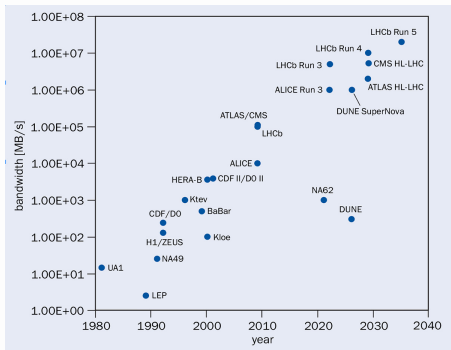
- **Reproduce** the behaviour → testing in collaboration with institutes to isolate the source (December)
- **Understand** the problem → **Irradiation** testing campaign (X-rays, 4 Co60 sources worldwide), **Irradiation programme in low-T environment scanning 5, 10, 20, 70 Mrad** (10 Mrad covers many users)
- **Advise** on mitigations (for v6): connect Enable and Vin pins together to limit the stress time and/or use the bPOL12V in low radiation environment and high temperature
- **Corrective solutions** → Modifications to circuit around bPOL12V; new version pin-compatible with old version.
- **Latest news** → Two new issues observed in recent large irradiation campaign to 80Mrad, impact on use of existing bPOL12V (v6) under study; New chip version (**FIX1**) is under production using new technology (**OnSemi I3T80**). Test on irradiated devices ongoing before validating the new solution

Consequence: unexpected delays due to stalled assembly while issue was being debugged: assembly progressing where solutions with bPOL12V v6 could be found, further delays where FIX1 is required

Stronger: The bandwidth issue

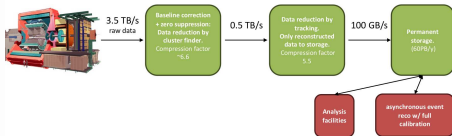
New Trigger strategies are key to empower physics reach of experiments. That will especially be the case for HL-LHC

- Profit from the event reconstruction / data reduction done by the trigger system
- “Real Time Analysis” both online (producing aggregated results) and offline
- Remove hardware trigger (ALICE and LHCb)
- **ALICE**: Continuous read-out of all detector data, with reduced data volume to disk
- **LHCb**: HLT1 partial event reconstruction on GPUs hosted in the event-building servers, HLT2 provided with real-time computed calibration constants, performs full event reconstruction on CPU

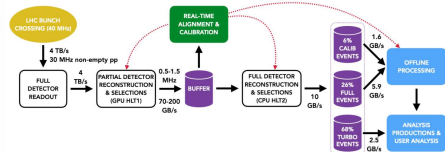


[credit to A. Cerri, University of Sussex]

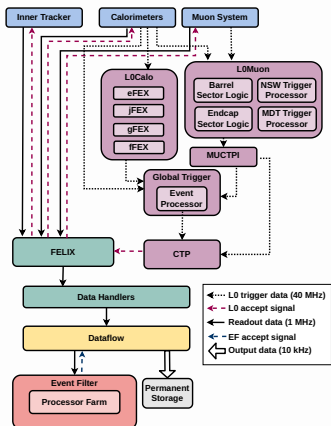
ALICE O² system
(common online-offline system)



LHCb RTA system

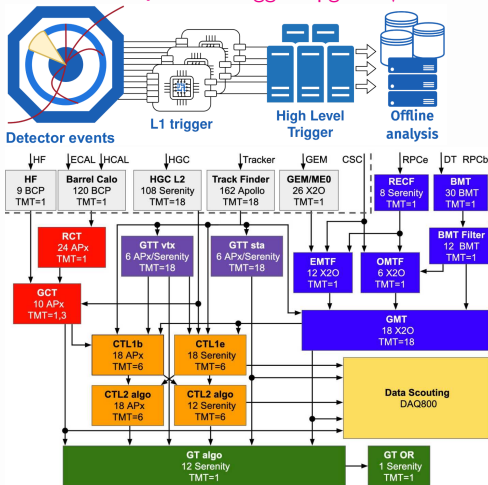


Stronger: Trigger strategies



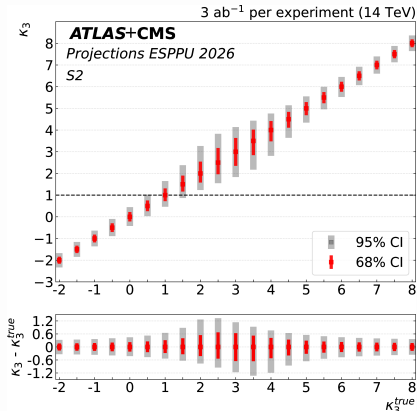
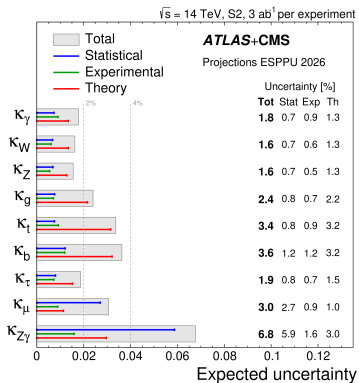
ATLAS L0: Full granularity data from Calorimeters, data from all muon detectors; global Trigger: offline-like algorithms to combine/refine regional candidates running on farm of common HW

← ATLAS TDAQ Upgrade
CMS DAQ and L1 trigger Upgrade ↓

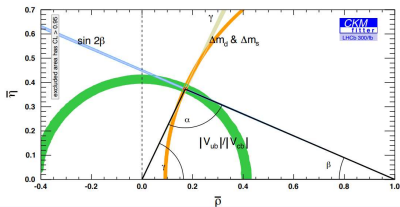
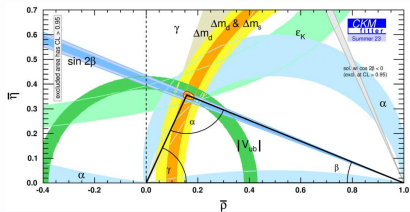


CMS L1: All detectors (but silicon-pixel detector) participating in providing primitives; information from sub-systems combine in an offline-like fashion by the Trigger-correlator

LHC Upgrades: Why?



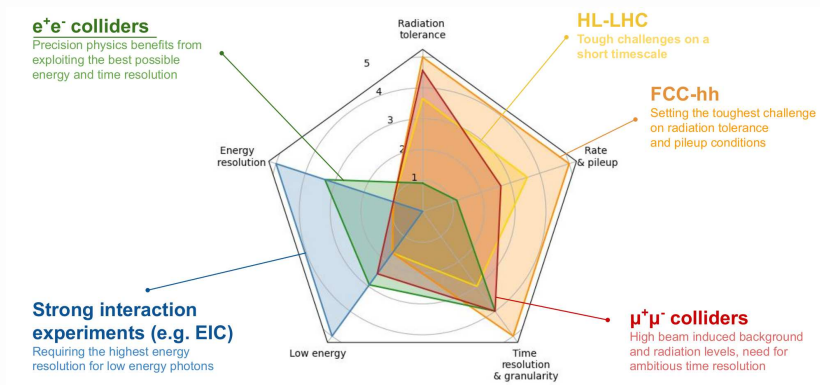
[ATL-PHYS-PUB-2025-018], [CMS-HIG-25-002], [LHCb-PUB-2025-001], [ALICE-PUBLIC-2025-005]



LHC Upgrades: Conclusions

Qualitative representation of requirements for calorimeters at future colliders

M. Lucchini's seminar on calorimeters for Future e^+e^- colliders



Much more can be found on the Input session of Future Facilities I

Technological advancements during HL-LHC era are mission critical for today's High Energy Physics programme but also for the Future Facilities

"The unique ecosystem of particle physics research centres and universities in Europe should be further strengthened in order to address the objectives set out in this Strategy." [CERN-ESU-2025-002]